

06-20-2003

FORM PTO-1595

(Rev. 10/02)

OMB No. 0651-0027 (exp. 6/30/2005)



SHEET

U.S. Department of Commerce
Patent and Trademark Office

102478751

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

6-17-03

NIPPON FOUNDRY, INC.
(formerly Nippon Steel Semiconductor Inc.)Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

Name and address of receiving party(ies)

Name
UNITED MICROELECTRONICS CORPORATION
No. 3 Hsin Road 2
Science Based Industrial Park
Hsin Chu City, TAIWANAdditional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ OtherExecution Date: **March 3, 1999**

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

B. Patent No.(s)

6,300,810

6,306,744

5,900,021

6,285,242

6,037,827

6,272,029

5,917,230

6,285,216

Additional numbers attached? ☐ Yes ☒ No

5. Name and Address of party to whom correspondence concerning document should be mailed:

Name: Carol W. BurtonInternal Address: Hogan & Hartson LLPOne Tabor Center1200 17th Street, Suite 1500Street Address: same as aboveCity: Denver State: CO Zip: 80202

6. Total number of applications and patents involved: 8

7. Total fee (37 CFR 3.41)

\$ 320.00☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

50-1123

(Attach duplicate copy of this page if paying by deposit account)

06/19/2003 DBYRNE 00000101 6300810

01 FC:8021

320.00 OP

DO NOT USE THIS SPACE

9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*Carol W. Burton

Name of Person signing

Signature

June 17, 2003

Date

Total number of pages including cover sheet, attachments and document: 3Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

ASSIGNMENT

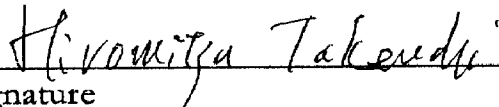
For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, *Nippon Foundry Inc.*, formerly known as *Nippon Steel Semiconductor Inc.*, having a principal place of business at No. 1580, Yamamoto, Tateyama-City, Chiba 294-8502 Japan ("Assignor"), hereby assigns, transfers, and conveys to *United Microelectronics Corporation* ("UMC"), having a principal place of business at No. 3 Li Hsin Road 2, Science Based Industrial Park, Hsin Chu City, Taiwan ("Assignee"), its designees, successors, assigns, and legal representatives, the entire right, title, and interest in and to the patents and applications listed in Exhibit A, attached hereto and made a part hereof, and any reexaminations, extensions, reissues, continuations and divisions thereof, and all proceeds from any of the foregoing (including all license royalties and proceeds of infringement suits), and any and all causes of actions (excepting claims against the United States of America) for past, present, and future infringement of any of the foregoing, including the right to collect royalties or damages for any such infringement and the right to sue on any such causes of action, for their own use and benefit and the use and benefit of their successors, assigns, and legal representatives, each and every of the foregoing rights, titles, and interests herein assigned to be held and enjoyed by Assignee, its successors, assigns, and legal representatives, as fully and entirely as the same would have been held and enjoyed by Assignors had this Assignment not been made.

A copy of the formal documents filed with the government of Japan changing the name of *Nippon Steel Semiconductor Corp.* to *Nippon Foundry Inc.* is attached hereto as Exhibit B.

IN TESTIMONY WHEREOF, Assignors have caused this Assignment to be duly executed in their names and behalf by affixing their hands and seals thereto by their designated officer, director, or agent, whose name and title appear below.

Executed at No. 1580 Yamamoto, Tateyama-City, Chiba 294-8502 Japan, and effective March 3, 1999.

Nippon Foundry Inc.
(formerly *Nippon Steel Semiconductor Corp.*)


Signature

Name: Hiromitsu Takeuchi
Title: President

Exhibit A
List of Patents and Applications Assigned to UMC

Case	Title	Patent/Serial No.	Country
209	Pad Input Select Circuit	5,900,021	US
209EPO		Patent No: EP869617 Application No: EP97630071.5	Europe
212	Noise Isolation Circuit	6,037,827	US
212EPO		Application No: EP97630089.7	Europe
214	Filter Capacitor	5,917,230	US
214EPO		Application No: EP97630075.6	Europe
214DV		09/344,854	US
215	Voltage Down Converter w/ Switched Hysteresis	Application serial no. 09/492,727 Provisional serial no. 60/118,736	US
215EPO		Patent No: EP1026689 Application No: EP00300886.9	Europe
215JPN		212568/2000	Japan
215KOR		10-2000-40159	Korea
217	Reference Voltage Shifter	Application serial no. 09/492,730 Provisional serial no. 60/118,677	US
217EPO		Patent No: EP1026690 Application No: EP00300887.7	Europe
217JPN		211185/2000	Japan
217KOR		10-2000-40156	Korea
218	Dynamic Regulation Scheme for High Speed Charge Pumps	Application serial no. 09/493,987 Provisional serial no. 60/118,724	US
218EPO		Patent No: EP1026691 Application No: EP00300888.5	Europe
218KOR		10-2000-40165	Korea
218JPN		213058/2000	Japan
222	High Speed Output	Application serial no. 09/213,764	US
222EPO		Patent No.: EP1014378 Application No: EP99310009.8	Europe
222JPN		189877/2000	Japan
222KOR		10-2000-0033152	Korea